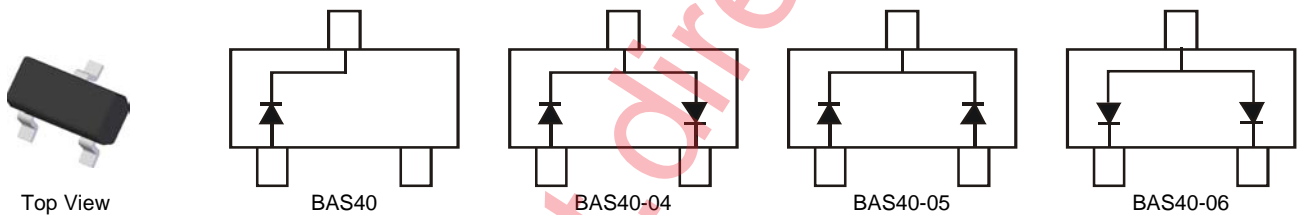


### Features

- Low Forward Voltage Drop
- Fast Switching
- PN Junction Guard Ring for Transient and ESD Protection
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

### Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Solderable per MIL-STD-202, Method 208 <sup>(e3)</sup>
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe).
- Polarity: See Diagrams Below
- Weight: 0.008 grams (approximate)

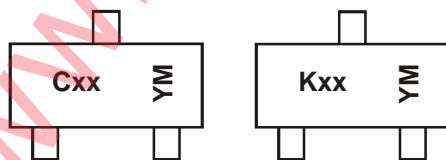


### Ordering Information (Note 4 & 5)

Part Number	Case	Packaging
BAS40-7-F	SOT23	3000/Tape & Reel
BAS40-04-7-F	SOT23	3000/Tape & Reel
BAS40-05-7-F	SOT23	3000/Tape & Reel
BAS40-06-7-F	SOT23	3000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See <http://www.diodes.com> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.
  5. Product manufactured with Date Code V9 (week 33, 2008) and newer are built with Green Molding Compound. Product manufactured prior to Date Code V9 are built with Non-Green Molding Compound and may contain Halogens or Sb<sub>2</sub>O<sub>3</sub> Fire Retardants.

### Marking Information



K=(SAT,Shangbai Assembly / test site)  
 C=(CAT / DTC , ChengDu Assembly / test site)  
 xx = Product Type Marking Code:  
 43 = BAS40  
 44 = BAS40-04  
 45 = BAS40-05  
 46 = BAS40-06  
 YM = Date Code Marking  
 Y = Year (ex: T = 2006)  
 M = Month (ex: 9 = September)

#### Date Code Key

Year	1999	2000	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015
Code	K	L	M	N	P	R	S	T	U	V	W	X	Y	Z	A	B	C
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec					
Code	1	2	3	4	5	6	7	8	9	O	N	D					

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V <sub>R</sub> RM	40	V
Working Peak Reverse Voltage	V <sub>R</sub> WM		
DC Blocking Voltage	V <sub>R</sub>		
Forward Continuous Current (Note 6)	I <sub>FM</sub>	200	mA
Forward Surge Current (Note 6) @ t < 1.0s	I <sub>FSM</sub>	600	mA

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P <sub>D</sub>	350	mW
Thermal Resistance, Junction to Ambient Air (Note 6)	R <sub>θJA</sub>	357	°C/W
Operating Temperature Range	T <sub>J</sub>	-55 to +125	°C
Storage Temperature Range	T <sub>STG</sub>	-65 to +150	°C

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	V <sub>(BR)R</sub>	40	—	—	V	I <sub>R</sub> = 10μA
Forward Voltage	V <sub>F</sub>	—	—	380 1000	mV	t <sub>p</sub> < 300μs, I <sub>F</sub> = 1.0mA t <sub>p</sub> < 300μs, I <sub>F</sub> = 40mA
Reverse Leakage Current (Note 7)	I <sub>R</sub>	—	20	200	nA	t <sub>p</sub> < 300μs, V <sub>R</sub> = 30V
Total Capacitance	C <sub>T</sub>	—	4.0	5.0	pF	V <sub>R</sub> = 0V, f = 1.0MHz
Reverse Recovery Time	t <sub>rr</sub>	—	—	5.0	ns	I <sub>F</sub> = I <sub>R</sub> = 10mA to I <sub>R</sub> = 1.0mA, R <sub>L</sub> = 100Ω

Notes: 6. Part mounted on FR-4 board with recommended pad layout, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.  
7. Short duration pulse test used to minimize self-heating effect.

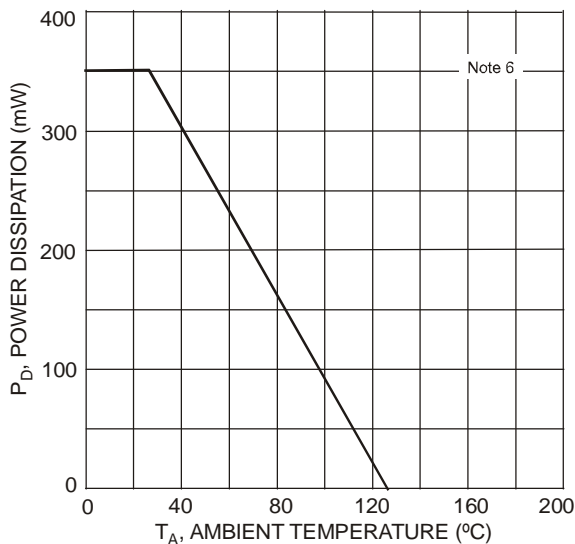


Figure 1 Power Derating Curve, Total Package

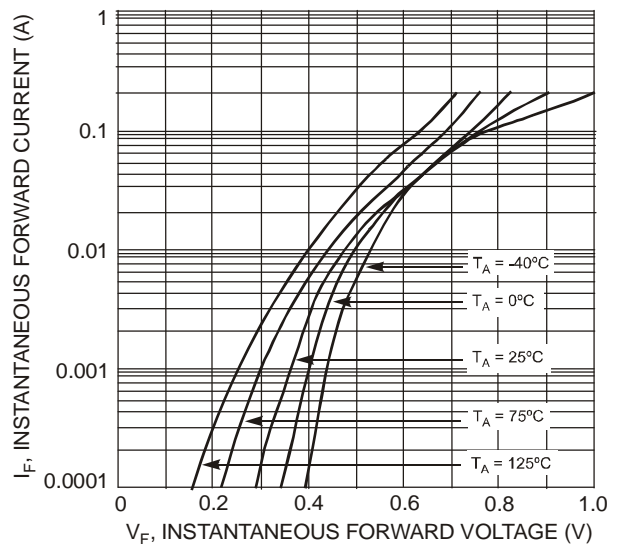


Figure 2 Typical Forward Characteristics

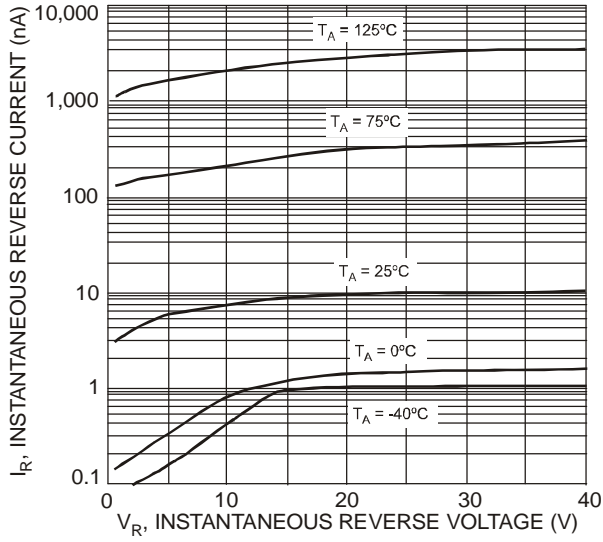


Figure 3 Typical Reverse Characteristics

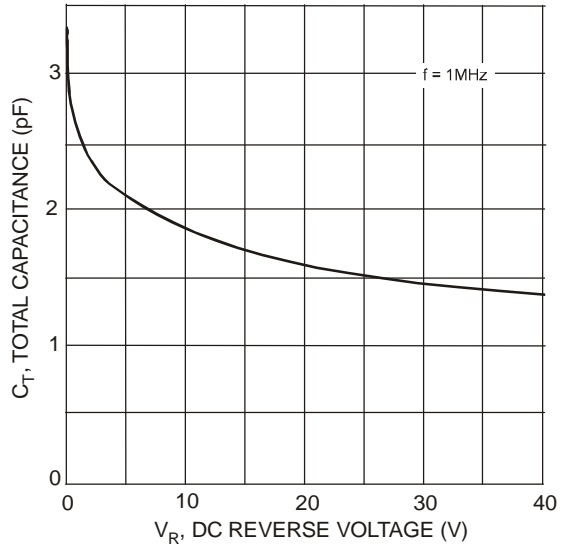
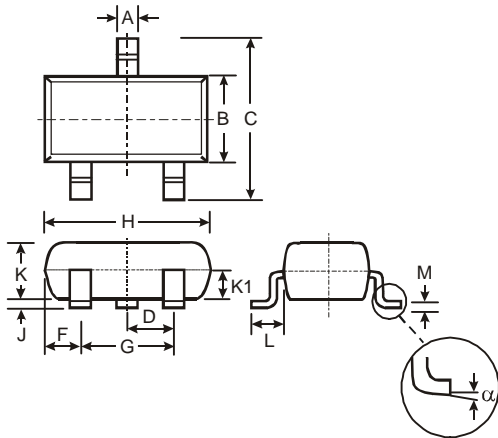


Figure 4 Total Capacitance vs. Reverse Voltage

**Package Outline Dimensions**

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.

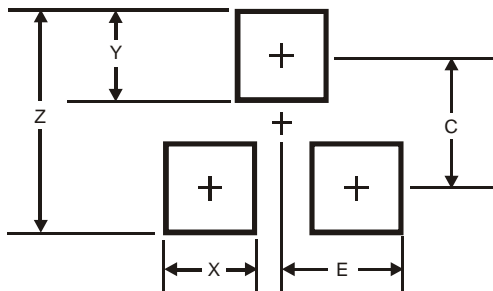


SOT23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.903	1.10	1.00
K1	-	-	0.400
L	0.45	0.61	0.55
M	0.085	0.18	0.11
α	0°	8°	-

All Dimensions in mm

**Suggested Pad Layout**

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

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